

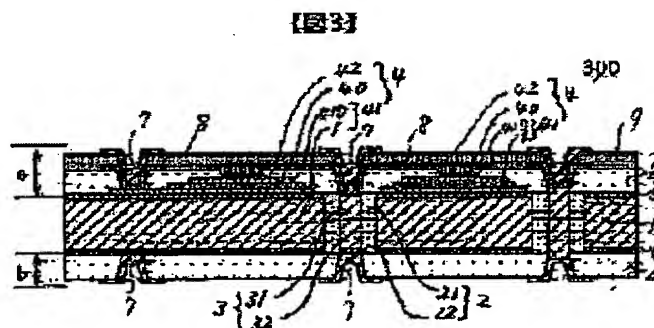
CIRCUIT BOARD INCORPORATING CAPACITOR, AND METHOD OF MANUFACTURING THE SAME

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Inventor: MATSUZAKI EIJI; ISHIHARA SHOSAKU; SHIGI
HIDETAKA; MATSUSHIMA NAOKI; ABE YOICHI
Applicant: HITACHI LTD
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- **International:** H01L23/12; H01L23/14
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Abstract of JP2001358248

PROBLEM TO BE SOLVED: To provide a semiconductor device which can reduce switching noise while avoiding reduction of a mounting density, by incorporating a decoupling capacitor providing a high capacity density in a circuit board as an interposer suitable when a semiconductor chip is mounted in the wiring board. **SOLUTION:** A conductive member is used as a base substrate of a circuit board a capacitor is formed on the base substrate to have the base substrate as its one electrode, a conductive via for electrical connection between front and back surfaces of the base substrate is provided in the base substrate through an insulating layer disposed therebetween, and mounting connection terminals are provided on the front and back sides of the circuit board.



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